# **GBJ200X SERIES**

## **GLASS PASSIVATED SINGLE-PHASE BRIDGE RECTIFIER**

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### **GBJ20005 THRU GBJ2010**

#### GLASS PASSIVATED SINGLE-PHASE BRIDGE RECTIFIER





REVERSE VOLTAGE: 50 to 1000 VOLTS FORWARD CURRENT: 20.0 AMPERE

#### **FEATURES**

· Glass passivated chip junction

· Reliable low cost construction utilizing molded plastic technique

· Ideal for printed circuit board

· Low forward voltage drop

· Low reverse leakage current

· High surge current capability

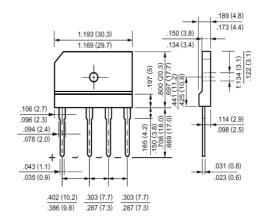
#### **MECHANICAL DATA**

Case: Molded plastic, GBJ

Epoxy: UL 94V-O rate flame retardant

Terminals: Leads solderable per MIL-STD-202,

method 208 guaranteed Mounting position: Any Weight: 0.23ounce, 6.6gram GBJ



Dimensions in inches and (millimeters)

#### Maximum Ratings and Electrical Characteristics

Ratings at 25 ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

	Symbols	GBJ20005	GBJ2001	GBJ2002	GBJ2004	GBJ2006	GBJ2008	GBJ2010	Units
Maximum Recurrent Peak Reverse Voltage	V <sub>RRM</sub>	50	100	200	400	600	800	1000	Volts
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	Volts
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	200	400	600	800	1000	Volts
Maximum Average Forward Rectified Current with Heatsink at $T_C$ =90	I <sub>(AV)</sub>	20.0							Amp
Peak Forward Surge Current, 8.3ms single half-sine-wave superimposed on rated load (JEDEC method)	I <sub>FSM</sub>	250							Amp
Maximum Forward Voltage Drop per Element at 10.0A DC and 25	$V_{\mathrm{F}}$	1.05							Volts
Maximum Reverse Current at T <sub>A</sub> =25 at Rated DC Blocking Voltage T <sub>A</sub> =125	$I_R$	10.0 500							uAmp
Typical Junction Capacitance (Note 1)	$C_{J}$	60							pF
Typical Thermal Resistance (Note 2)	$R_{\theta JC}$	0.8							<b>/W</b>
Operating and Storage Temperature Range	T <sub>J</sub> , Tstg	-55 to +150							

#### NOTES:

- 1- Measured at 1 MHz and applied reverse voltage of 4.0 VDC.
- 2- Thermal Resistance from Junction to Case with Device Mounted on 300mm x 300mm x 1.6mmCu Plate Heatsink.





#### RATINGS AND CHARACTERISTIC CURVES

